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ABSTRACT OF THE DISCLOSURE

0028 Chamber-reversed dry etching is disclosed. A semiconductor dry etching system can include a plasma chamber, a wafer lifter, a wafer chuck, and a bias supply. Polymer is introduced into the plasma chamber, such that excess polymer forms and subsequently peels off the inner vertical walls of the chamber, and falls down due to gravity. The wafer lifter holds the semiconductor wafer upside-down over the plasma chamber, preventing the excess polymer from falling onto the wafer. The wafer chuck moves the wafer upside-down to over the plasma chamber for the wafer lifter to hold the wafer upside-down over the plasma chamber. The bias supply biases the wafer, such that the polymer is electro-statically attracted to the wafer.